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ABSTRACT

A semiconductor assembly (10) in which a semiconductor chip (12) is secured to a die pad (14) is placed in a cavity (38). A support pin (42) which is able to enter into or be pulled out of the cavity (38) is provided in a lower mold (36). The support pin (42) is provided on the axis of a mold gate provided in the lower mold (36) and can be moved up and down by a servomotor (48). The support pin (42) comes in contact with the bottom of the die pad (14) to support the semiconductor assembly (10), thereby preventing the semiconductor assembly (10) from tilting or moving up and down due to the flow of the resin injected into the cavity (38).

